



GBJ8005 THRU GBJ810

GLASS PASSIVATED BRIDGE RECTIFIER

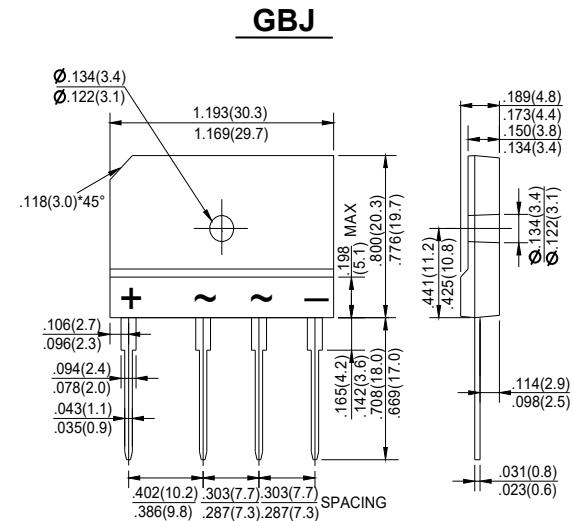
Reverse Voltage - 50 to 1000 Volts Forward Current - 8.0 Ampere

FEATURES

- Glass passivated chip junction
- Reliable low cost construction utilizing molded plastic technique
- Ideal for printed circuit board
- Low reverse leakage current
- Low forward voltage drop
- High surge current capability

MECHANICAL DATA

- Case: Molded plastic, GBJ
- Terminals: Leads solderable per MIL-STD-202 method 208 guaranteed
- Epoxy: UL 94V-0 rate flame retardant
- Mounting Position: Any



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	GBJ 8005	GBJ 801	GBJ 802	GBJ 804	GBJ 806	GBJ 808	GBJ 810	Units
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current with Heatsink at T _C = 100 °C	I _(AV)					10			A
Peak Forward Surge Current, 8.3 ms Single Half-Sine -Wave superimposed on rated load (JEDEC Method)	I _{FSM}					170			A
Maximum Forward Voltage at 4.0 A DC and 25 °C	V _F				1.1				V
Maximum Reverse Current at T _A = 25 °C at Rated DC Blocking Voltage T _A = 125 °C	I _R				5.0				µA
Typical Junction Capacitance ¹⁾	C _J				55				pF
Typical Thermal Resistance ²⁾	R _{θJC}				1.6				°C/W
Operating and Storage Temperature Range	T _J , T _S				-55 to +150				°C

¹⁾ Measured at 1 MHz and applied reverse voltage of 4 VDC.

²⁾ Thermal resistance from junction to case with device mounted on 300 mm X 300 mm X 1.6 mm Cu plate heatsink.



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RATINGS AND CHARACTERISTIC CURVES

